

## **REMARKS**

Claims 5-13 are pending and under consideration. Claims 1-4 were withdrawn pursuant to a restriction requirement.

In the Office Action of February 12, 2004, claims 5-13 were rejected and various minor objections were raised against some claims and certain portions of the specification.

In response, independent claims 5, 8 and 11 have been amended, and the specification has been amended.

Regarding the objections to the specification, the examiner's comments have been taken into account in the amendment. It is submitted that the various objections have been addressed adequately and that the objections can be withdrawn.

Regarding the rejection of the claims in view of the prior art, the rejection is traversed.

Each of independent claims 5, 8 and 11 recites a method in which a filling layer is interposed between wirings in a semiconductor device, wherein the filling layer comprises:

a non-fluorine system polymer selected from the group consisting of BCB, poly-aryl-ether, polyimide, and like effective non-fluorine system polymers,

a fluorine system polymer selected from the group consisting of a fluorine addition polymer, tetra-fluoro ethylene, cyclo-perfluoro carbon, poly-aryl-fluoride ether, fluorine addition parylene, and like effective fluorine system polymers,

organic SOG,

silicon oxide system xerogel,

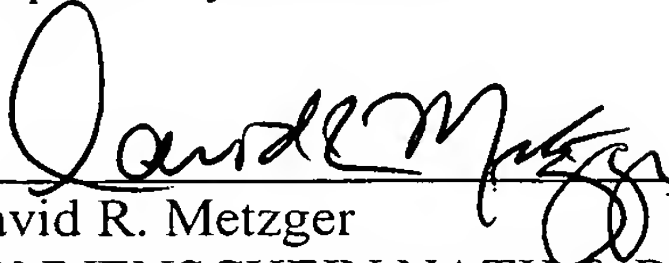
nano-porous silica, or

amorphous carbon.

It is submitted that none of the cited references fairly discloses or suggest wiring methods in which such a filling layer is used. Accordingly, it is submitted that the claims are patentable.

In view of the foregoing it is submitted that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,

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